



International Microsystems , Packaging,
Assembly and Circuits Technology conference

IMPACT 2012 Call for Papers is starting!!
Please submit your abstract before June 15!
Accepted Papers Will Be Collected in IEEE Xplore!

International Microsystems, Packaging, Assembly and Circuits Technology Conference—IMPACT 2012 call for paper is starting now! In 2012, system scaling & integration is coming to the central stage of electronics product and service. Most importantly, MG+4C, i.e. Medical, Green, Automobile (Car), Computer, Communication & Consumer applications, with system scaling and integration are among the most potential electronics. Among these fields, do you have any new discovery or stunning research? Summit your paper to IMPACT conference before June 15th which is truly your best access and practice to this new paradigm shift.

IMPACT 2012 which is jointly organized by IEEE CPMT-Taipei, iMAPS-Taiwan, ITRI and TPCA, and co-organized by IDB, ISU, NK, NTU, SMTA and TTMA will be held in conjunction with TPCA Show on Oct. 24-26, 2012, at Taipei Nangang Exhibition Hall. To construct a complete spectrum of technology trends, the theme of IMPACT 2012 highlights “IMPACT, Inspiring Innovation” and will present invited talks, workshop, industrial sessions and selected paper presentations. Furthermore, IMPACT keeps collaborating with International organizations such as ICEP from Japan and iNEMI from U.S.A.

The series of IMPACT conferences has been acknowledged as successful annual gathering to share high quality papers and facilitate international participation. IMPACT 2012 whole-heartedly invites paper submissions from researchers in academia, industries and research institutes. Your participation is a key to cross-domain communication and inter-field innovation.

Conference: IMPACT 2012

Exhibition: TPCA Show 2012

Theme: **IMPACT, Inspiring Innovation**

Date: Oct 24th (Wed.)-26th (Fri.), 2012

Venue: Taipei Nangang Exhibition Hall

On-line Submission : <http://www.impact.org.tw/2012/Submission/>

SCOPE OF PAPER SOLICITED

Packaging	PCB
P1 -Advanced Packaging Technologies	B1-Materials and Process
P2. Power Module and Green Packaging	B2-Test, Quality, Inspection and Reliability Technology
P3-3D Integration	B3-Build-up/HDI and Embedded Technology
P4-LED & Optoelectronics Packaging	B4-Electro Deposition and Electrochemical Processing Technology
P5-Interconnections & Nanotechnology	B5-Surface Mounting and Assembly Technology
P6-Modeling, Simulation & Design	B6-Advanced and Emerging Technology
P7-Thermal Management	B7-Mechatronics and Automation



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P8- Advanced Sensor & Microsystems Technology (MST)	B8-Marketing & Management
P9-Advanced Materials, Process & Assembly	
P10-Emerging Systems Packaging Technologies	

* Papers relevant with the above scopes are encouraged to submit but NOT limited to.

* Conference authority keeps the right to final session arrangement.

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline	June 15, 2012	400-500 words Submit on-line through conference website
Abstract Acceptance Notification	July 10, 2012	Notice sent via email
Full Paper Submission (Camera-ready Version)	August 15, 2012	4 pages including figures and tables Submit on-line through conference website
Advanced Program & Pre-registration announcement	September 1, 2012	Final session arrangement and announce advanced program
Presentation Material Submission (Oral Presentation)	October 1, 2012	15 minutes presentation with 3 minutes Q&A. Please email it to the secretariat

Contact Window

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